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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

APPLICANT: ELENUS, PETER ET AL.

FILING DATE
May 19, 2000

GROUP 1725

#2

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	EXHIBIT NUMBER	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>MP</i>	—	5,220,200	6/15/93	Blanton			
<i>MP</i>	—	5,261,593	11/16/93	Casson, et al.			
<i>MP</i>	—	5,547,740	8/20/96	Higdon, et al.			
<i>MP</i>	—	5,564,617	10/15/96	Degani, et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	EXHIBIT NUMBER	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>MP</i>	—	Brakke, Kenneth A., Mathematics Department, Susquehanna University, Selinsgrove, PA 17870, excerpts from the Web site for "The Surface Evolver", Version 2.14, dated August 18, 1999, including Surface Evolver Overview; Surface Evolver Documentation: Example: Column of Liquid Solder; Newsletter No. 2 (2/26/93); and Newsletter No. 8 (6/23/94).
<i>MP</i>	—	Brandenburg, Scott and Yeh, Shing, "Electromigration Studies Of Flip Chip Bump Solder Joints", <i>Proceedings Surface Mount International 1998</i> , September 1998.

EXAMINER

Nitin Parikh

DATE CONSIDERED

09/25/01

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

